



VMDSEMI

VUTL006R110NA

Datasheet



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General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
60V	11mΩ@10V	75A

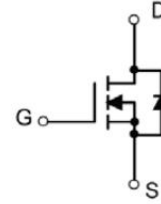
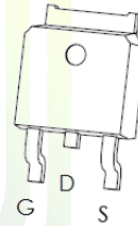


Figure 1 Symbol of VUTL006R110NA

Features

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100% ΔV_{DS} Tested

Package Type



TO-252-2L

Application

- Power switching application

Figure 2 Package Type of VUTL006R110NA

Ordering Information

Product Name	Package
VUTL006R110NA	TO-252-2L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1} $T_C = 25\text{ °C}$	I_D	75	A
Continuous Drain Current ^{Note1} $T_C = 100\text{ °C}$		50	
Continuous Drain Current ^{Note6} $T_A = 25\text{ °C}$		13	
Pulsed Drain Current ^{Note2}	I_{DM}	225	
Single Pulse Avalanche Energy ^{Note3}	I_{AS}	29	
Single Pulse Avalanche Energy ^{Note3}	E_{AS}	210	mJ
Total Power Dissipation ^{Note5}	P_D	83	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.5		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=48V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	3	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		9.5	11	mΩ
Forward transconductance ^{Note4}	g_{FS}	$V_{DS}=5V, I_D=20A$	20			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=30V$		2682		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		174		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		158		pF
Total Gate Charge	Q_g	$V_{DS}=30V$		50		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		15		
Gate-Drain Charge	Q_{gd}	$I_D=20A$		21		
Gate Resistance	R_g	$f = 1MHz, \text{Open Drain}$		2		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V$		20		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		12		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.5\Omega$		44		
Turn-off Fall Time	t_f	$R_G=3.0\Omega$		15		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=20A$			1.2	V

Notes :

- The maximum current rating is limited by package. And device mounted on a large heatsink
- Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- E_{AS} condition: $V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$. And device mounted on a large heatsink
- Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

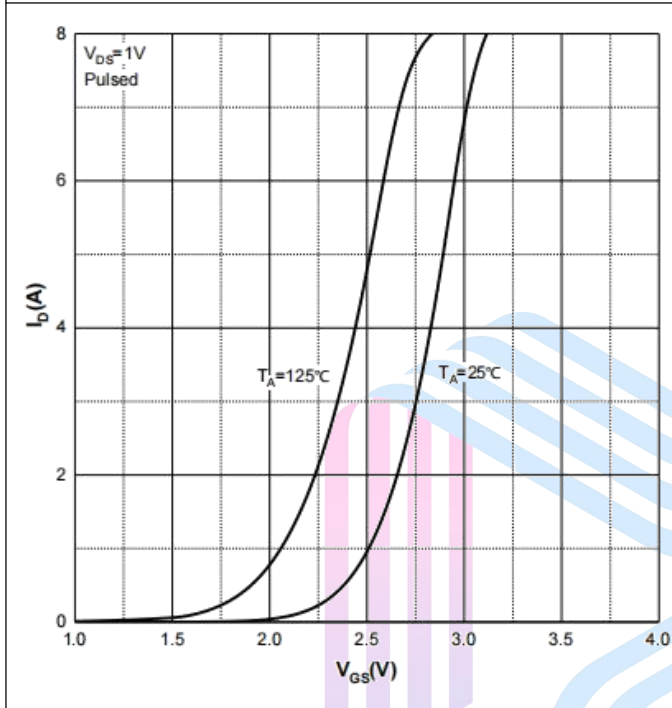
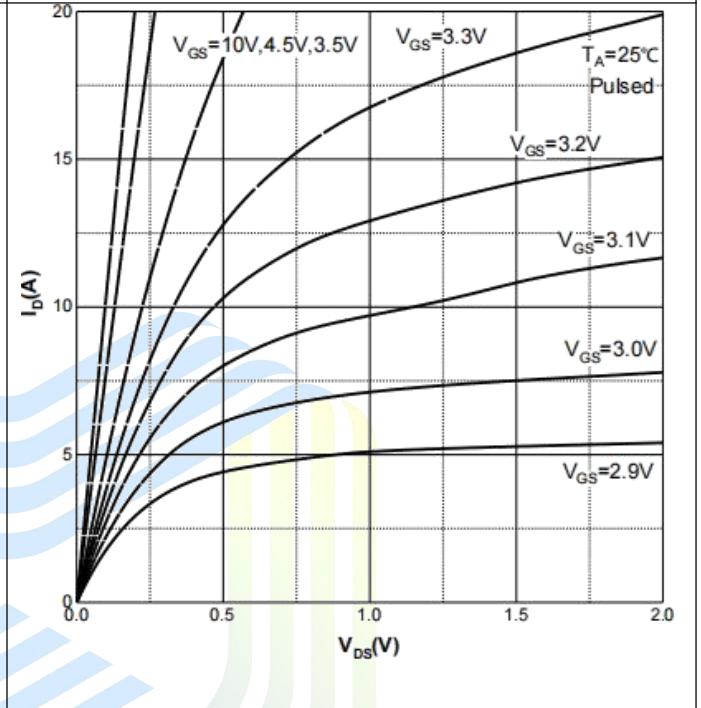
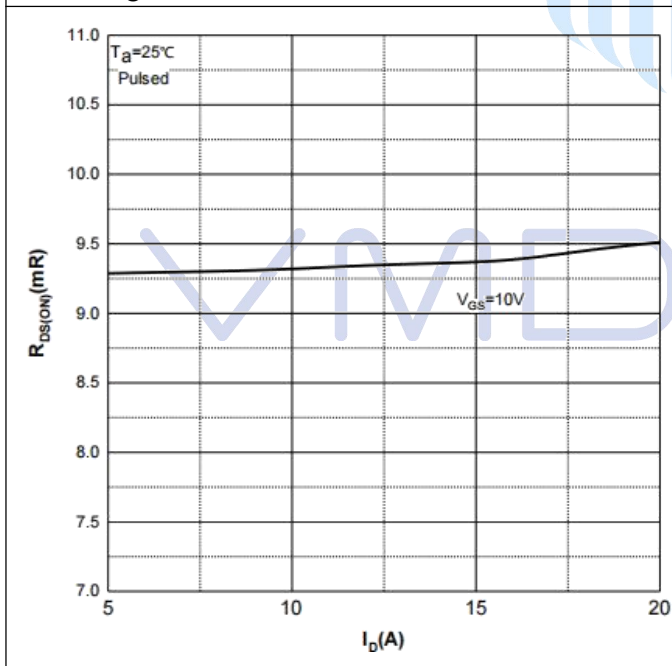
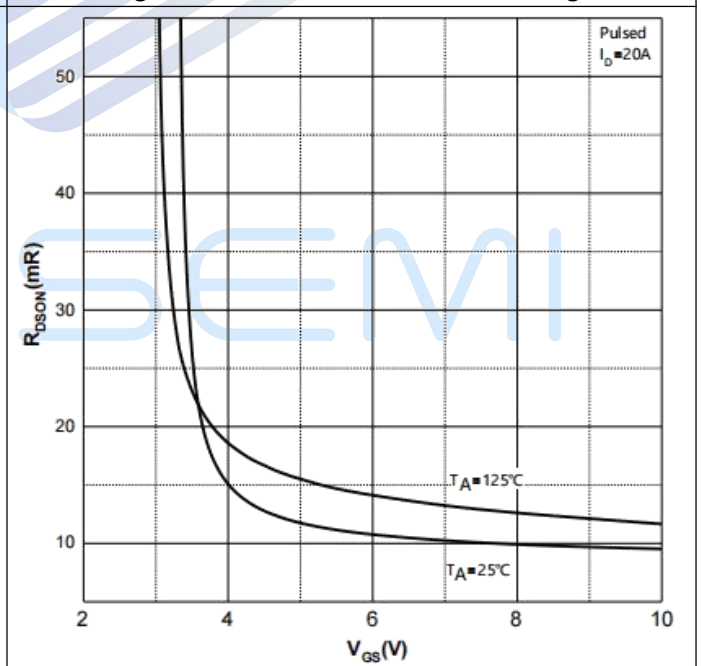
Typical Performance Characteristics
Figure 3: Transfer Characteristics

Figure 4: Output Characteristics

Figure 5: On-Resistance vs. Drain Current

Figure 6: On-Resistance vs. Gate Voltage


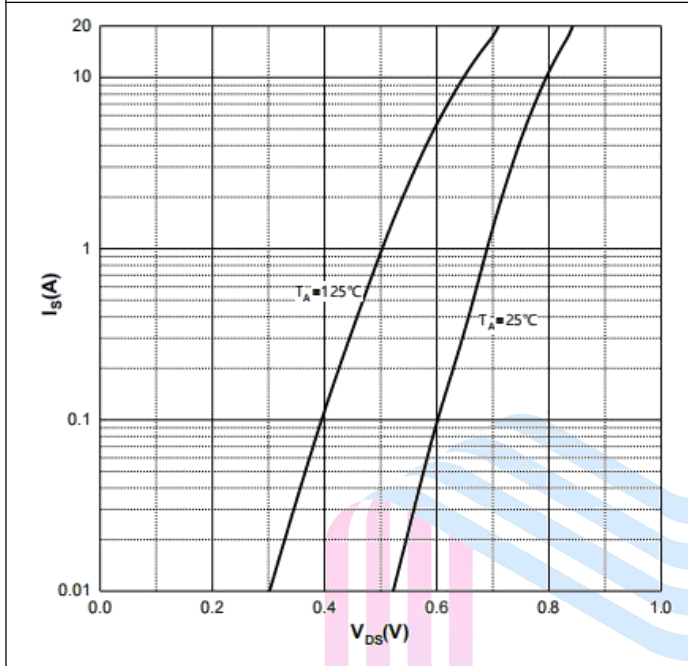
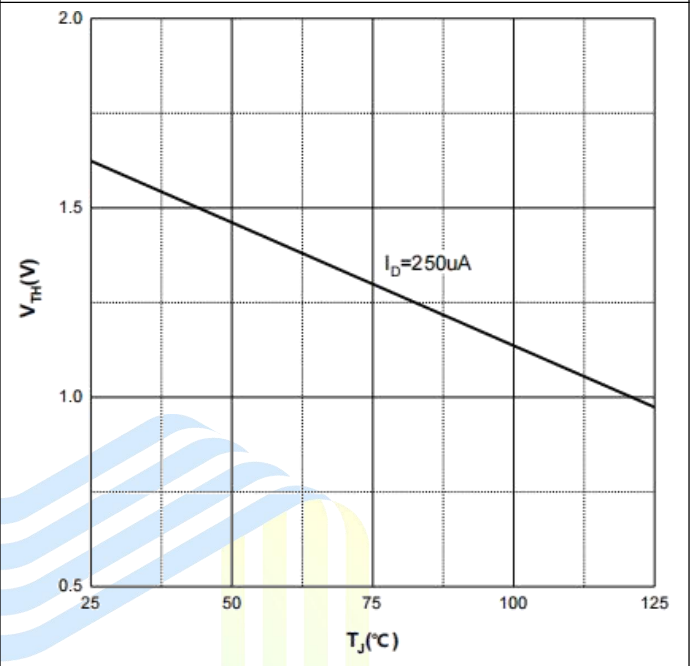
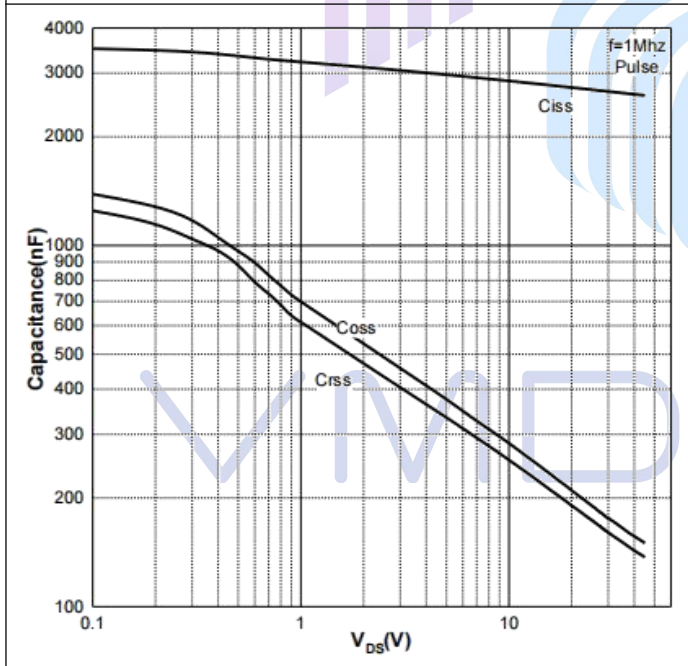
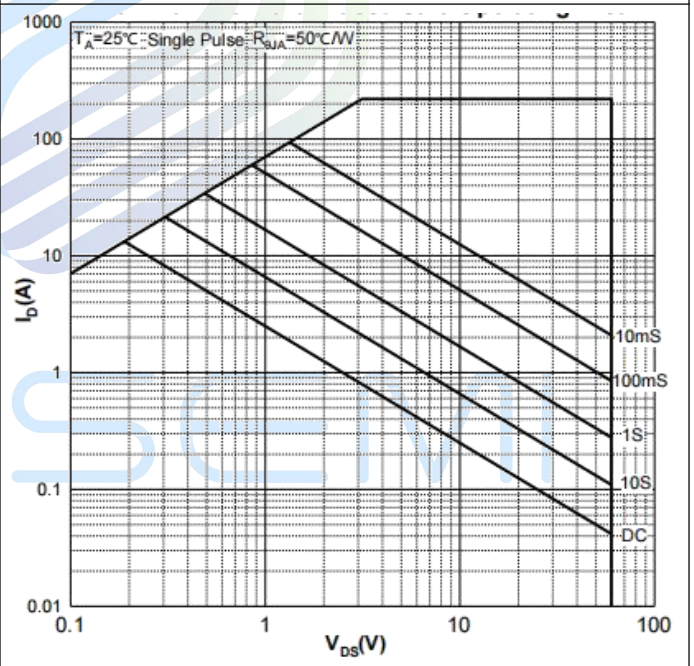
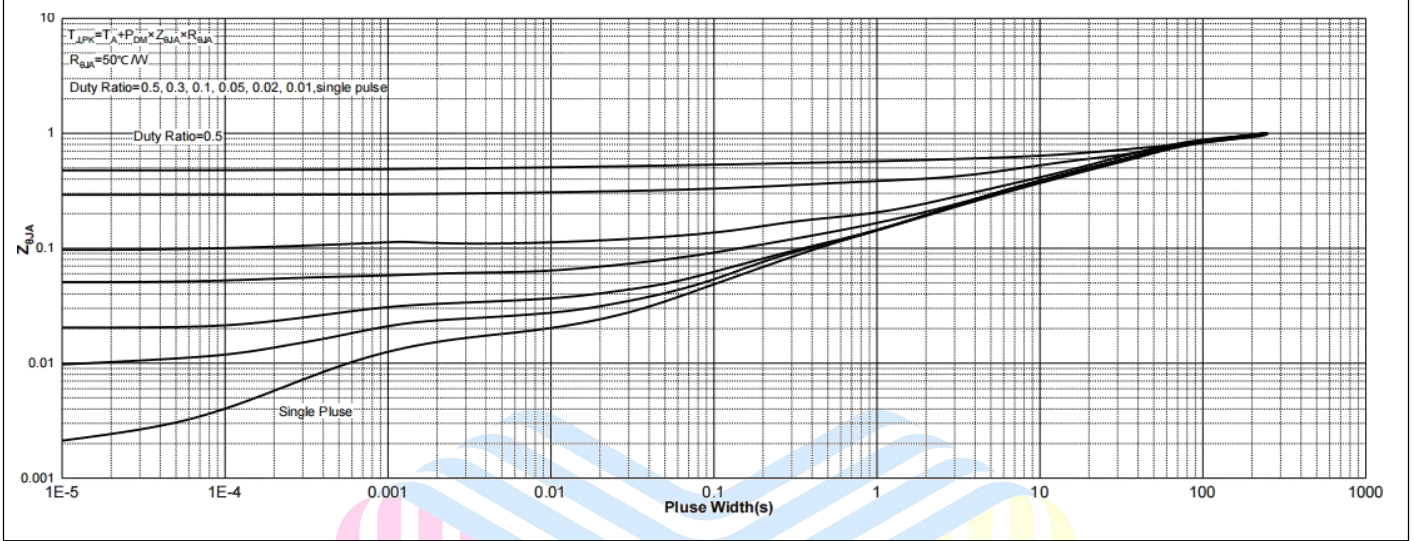
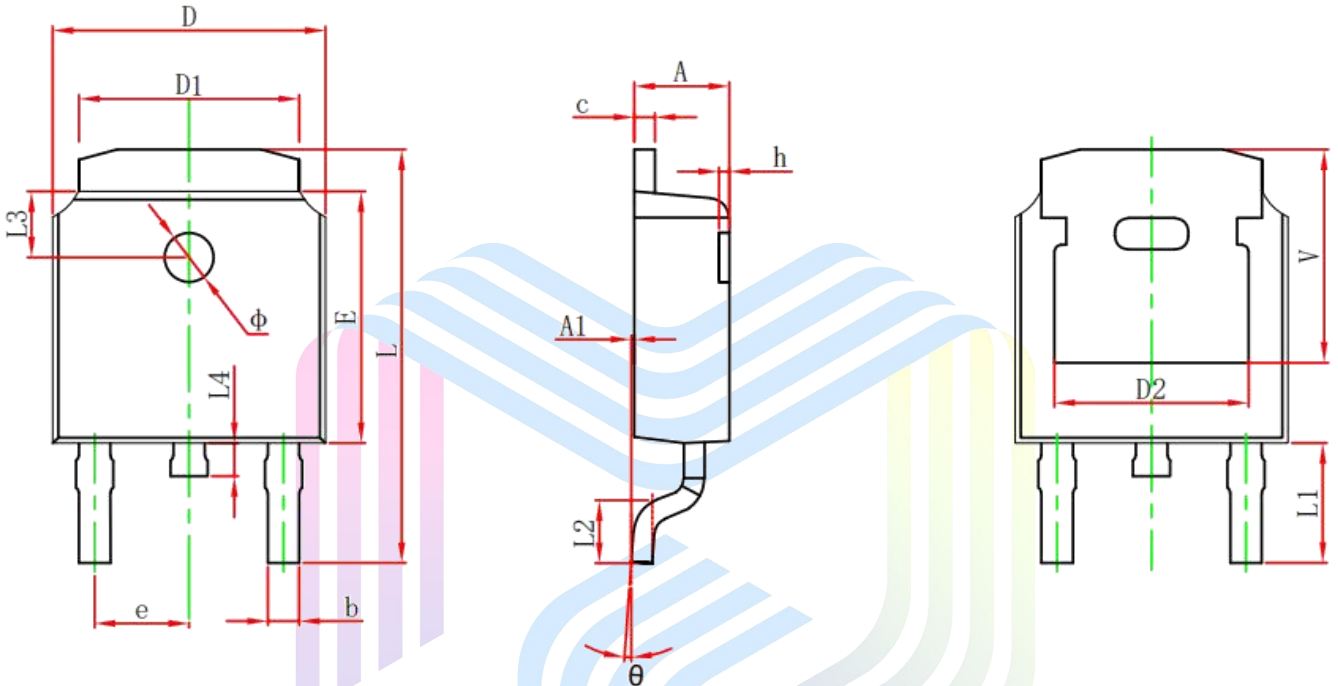
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance



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Mechanical Dimensions:
TO-252-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

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